EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	1817	438/455.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/14 10:42
L4	367	438/456.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/14 10:42
L5	1413	(L3 or L4) and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/14 10:42
L6	32	L5 and (SOI same (chip or die) same (bond$3 or connect$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/14 10:42
L7	0	((via near10 ((buried adj oxide) or BOX) near10 liner) same (interconnect $3 or plug)) and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/14 11:05
L8	13	(((trench or opening or hole) near10 ((buried adj oxide) or BOX) near10 liner) same (interconnect $3 or plug)) and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/14 11:05
L10	23	(((trench or opening or hole) near10 ((buried adj oxide) or BOX.u/c.) near10 (dielectric or insulat$3)) same (interconnect$3 or plug)) and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/14 11:07

L11	84	L5 and ((glass or silica) near5 (paste or epoxy or glue or adhesive)) and ((silicon or semiconduct $3) near5 (wafer or substrate)) and (die or chip)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/14 11:31
S1	1	10/595303	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 10:44
S2	13	Knechtel-Roy.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 10:11
S3	1	S2 and (paste and wafer and temperature).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 10:11
S4	1	X-Fab.as. and (paste and wafer and temperature).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 10:12
S5	1817	438/455.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 10:14
S6	367	438/456.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 10:14
S7	1413	(S5 or S6) and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 10:14

S9	1358	257/704.ccls. and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 10:15
S10	1819	(257/E21.211).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/13 10:17
S11	1698	(257/E23.193).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/13 10:17
S13	11	S7 and (glass near5 paste)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 10:22
S14	166	S7 and ((glass or silica) near5 (paste or resin or glue or epoxy or adhesive))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 10:29
S15	288	(((glass or silica) near5 (paste or epoxy or resin or adhesive or glue)) same conduct$3 same (non-conduct$3 or nonconduct$3)) and (melt$3 or premelt$3) and (Celsius or temperature) and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 10:39
S16	65	S15 and ((semiconduct$3 or silicon) near5 (wafer or substrate))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 10:52
S17	65	S16 and conduct$3 and (non-conduct$3 or nonconduct$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 10:56

S19	10	US-5164328-$.DID. OR US-5955771-$.DID. OR US-6020646-$.DID. OR US-6517399-$.DID. OR US-20020086456-$.DID.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 13:24
S20	1817	438/455.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 22:05
S21	367	438/456.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 22:05
S22	1413	(S20 or S21) and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 22:05
S23	106	S22 and ((semiconduct$3 near5 (wafer or substrate)) same bond$3 same ((semiconduct$3 or silicon) near5 (chip or die)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/13 22:05

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